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TC 1700

PATENT 0171-0759P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

Shoichi OSADA et al. Conf.:

9440

Appl. No.:

09/883,276

Group:

1712

Filed:

June 19, 2001

Examiner: Marc ZIMMER

For:

SEMICONDUCTOR ENCAPSULATING EPOXY RESIN

COMPOSITION AND SEMICONDUCTOR DEVICE

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 July 1, 2003

Sir:

Transmitted herewith is an amendment in the above-identified application.

The enclosed of	document is	being	transmit	ced via	the	Certificate
of Mailing pr	ovisions of	37 C.	F.R. § 1	.8.		

The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	10	-	20	=	0	\$ 18	\$0.00
INDEPENDENT	3	-	3	=	0	\$ 84	\$0.00
FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM							\$0.00
						TOTAL	\$0.00

Appl. No. 09/883,276

		month(s) extension of time pursuant to 1.136(a). \$0.00 for the extension of
\boxtimes	No fee is required.	
	Check(s) in the amount	of \$0.00 is(are) enclosed.
	Please charge Deposit 2 \$0.00. This form is sub	Account No. 02-2448 in the amount of mitted in triplicate.
overg requi	urrent, and future replications are appropriately and future replications.	ssioner is hereby authorized in this, ies, to charge payment or credit any at No. 02-2448 for any additional fees 1.16 or under 37 C.F.R. § 1.17; ime fees.
		Respectfully submitted,
		BIRCH, STEWART, KOLASCH & BIRCH, LLP
		By Meikle, #32,868
•	G:gml ·0759P	P.O. Box 747 Falls Church, VA 22040-0747 (703) 205-8000
Attac	chment(s)	(Rev. 04/30/03)